

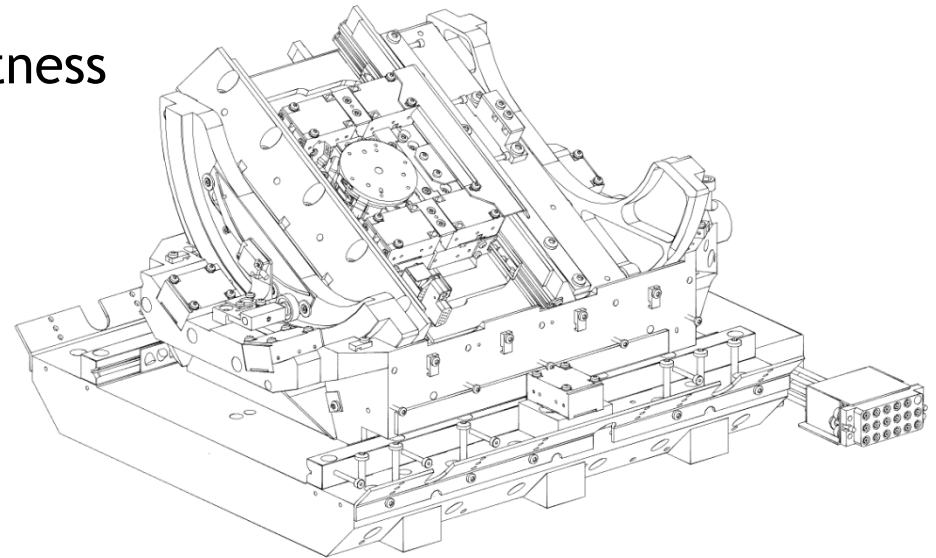
# Vybrané kapitoly z elektronové mikroskopie

## Sample manipulation

Frantisek Vaske

# General requirements for sample manipulator

- Stands still - no vibrations
  - High stiffness, low mass
- Stands still - no drift
  - Temperature stability
- Vacuum compatibility and tightness
- Non magnetic
- Moves the sample
  - Accuracy
  - Repeatability



# General requirements for sample manipulator

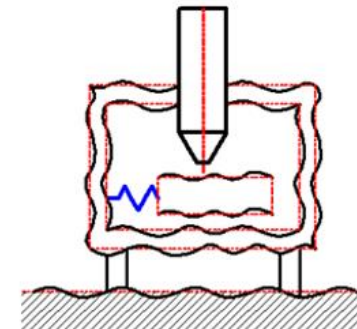
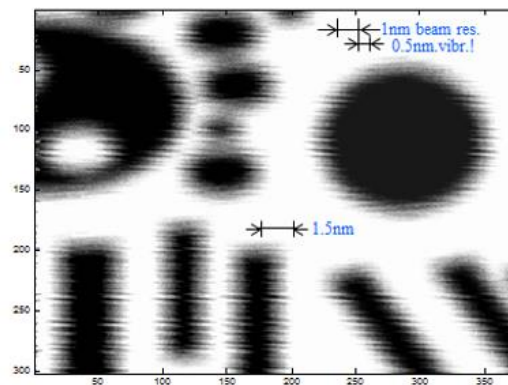
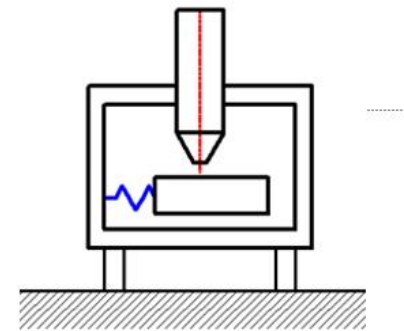
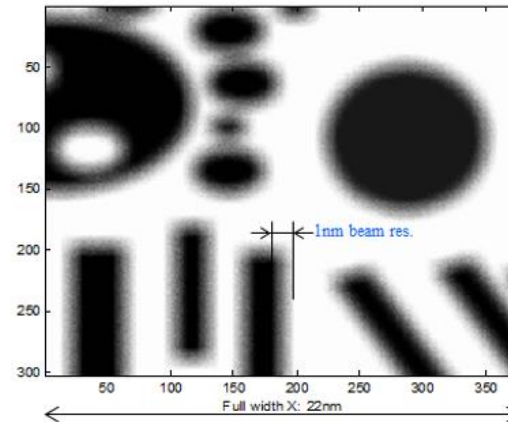
## No vibrations

Sources of vibrations

- Floor vibrations
- Accoustics



Loss of resolution  
Image flags – SEM  
specific (resolution, dwell)



# General requirements for sample manipulator

No vibrations

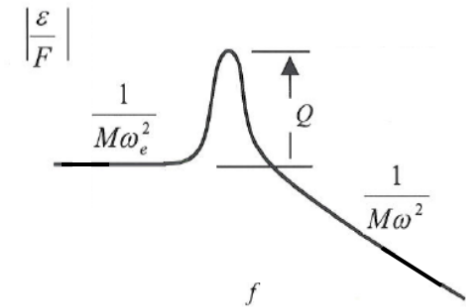
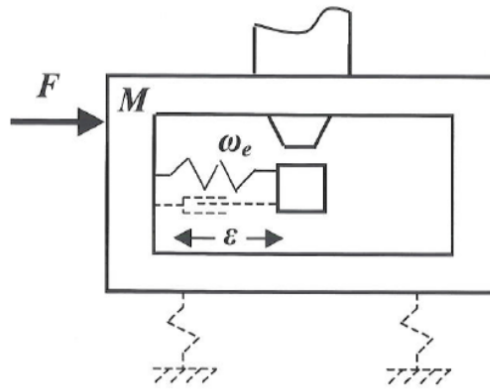


# General requirements for sample manipulator

No vibrations

## Increase stiffness

- Lightweight stage
- Friction brakes
- Herthzian contact in bearings



## Increase damping

- Tuned mass damper

Strive for:

High  $M$

high  $\omega_e$

Low  $Q$

# General requirements for sample manipulator

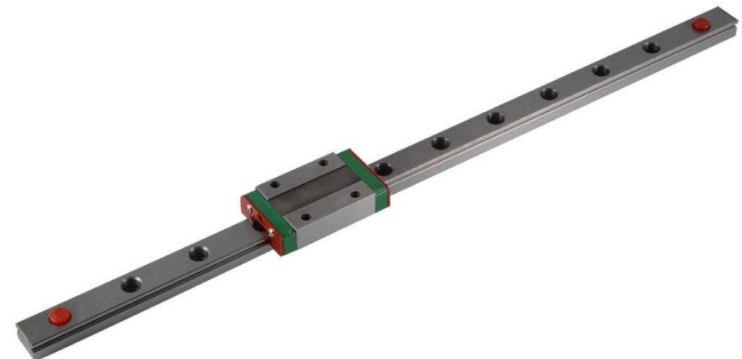
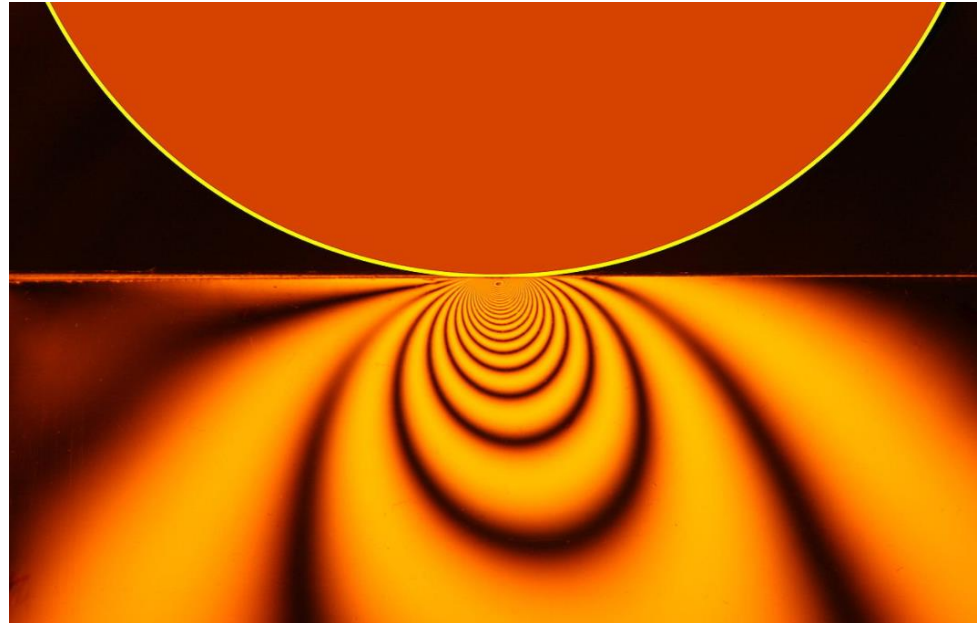
No vibrations

## Increase stiffness

- Lightweight stage
- Friction brakes
- Herthzian contact in bearings

## Increase damping

- Tuned mass damper



# General requirements for sample manipulator

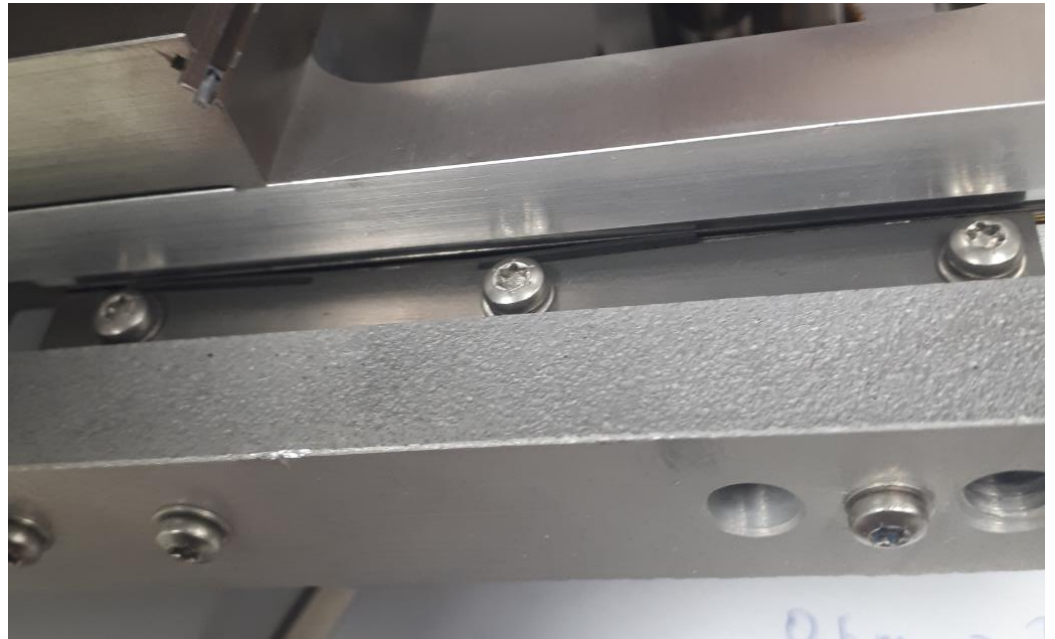
No vibrations

## Increase stiffness

- Lightweight stage
- Friction brakes
- Herthzian contact in bearings

## Increase damping

- Tuned mass damper



# General requirements for sample manipulator

No vibrations

## Increase damping

- Tuned mass damper



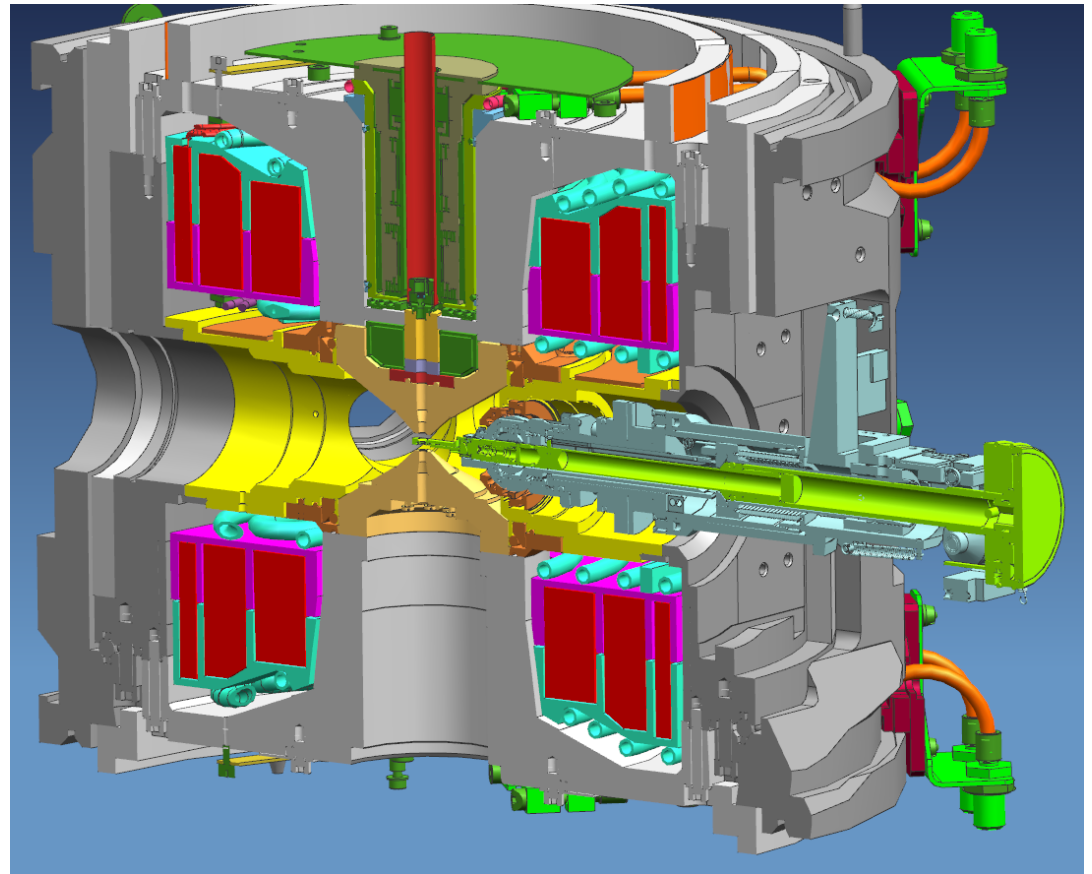


# General requirements for sample manipulator

## Thermal drift

- **Thermal drift**
  - Caused by thermal expansion
    - Temperature stability
    - Smart design

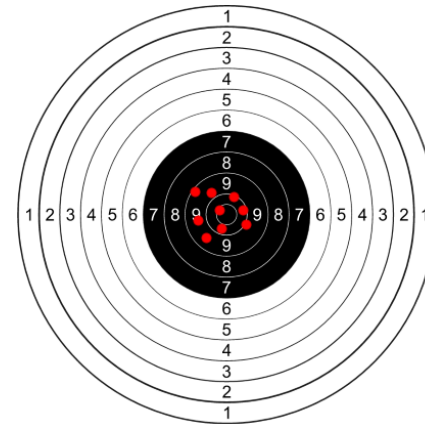
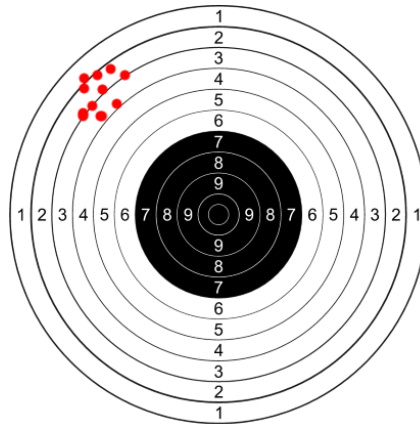
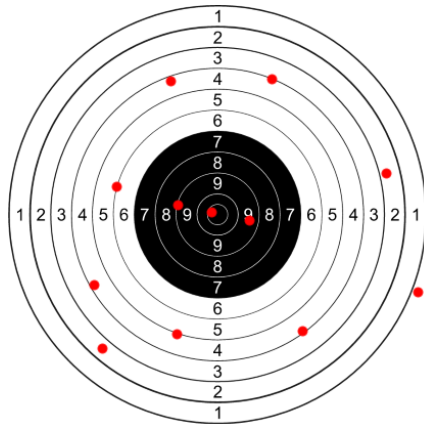
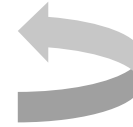
$$\text{drift} = L_0 \alpha (T_1 - T_0) / t$$



# General requirements for sample manipulator

## Motion

- Accuracy
- Repeatability – more important, can be calibrated
- Feedback control, mapping

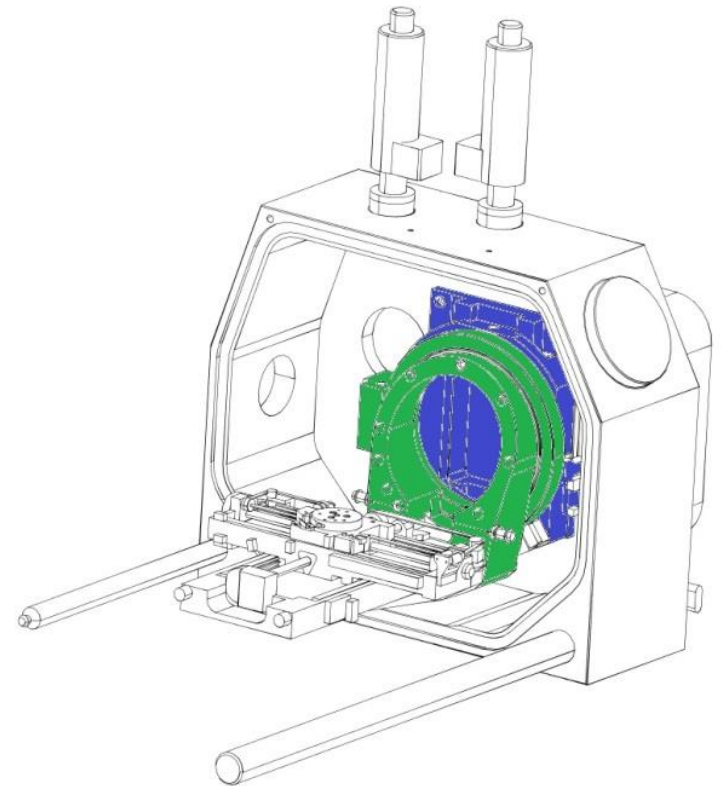
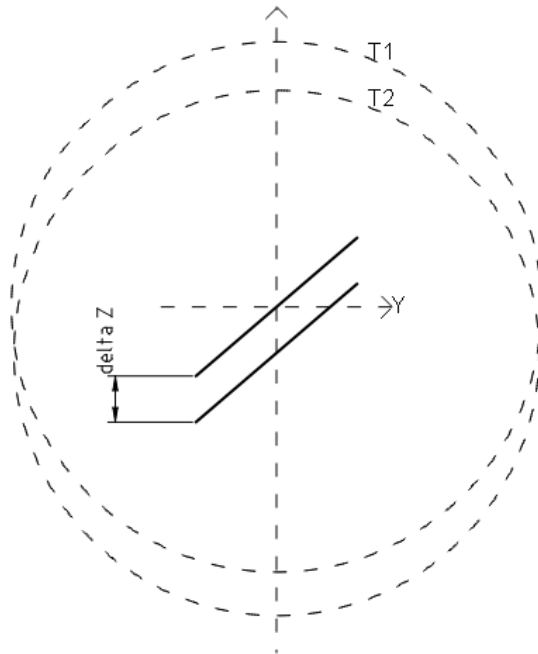


# General requirements for sample manipulator

## Eucentricity

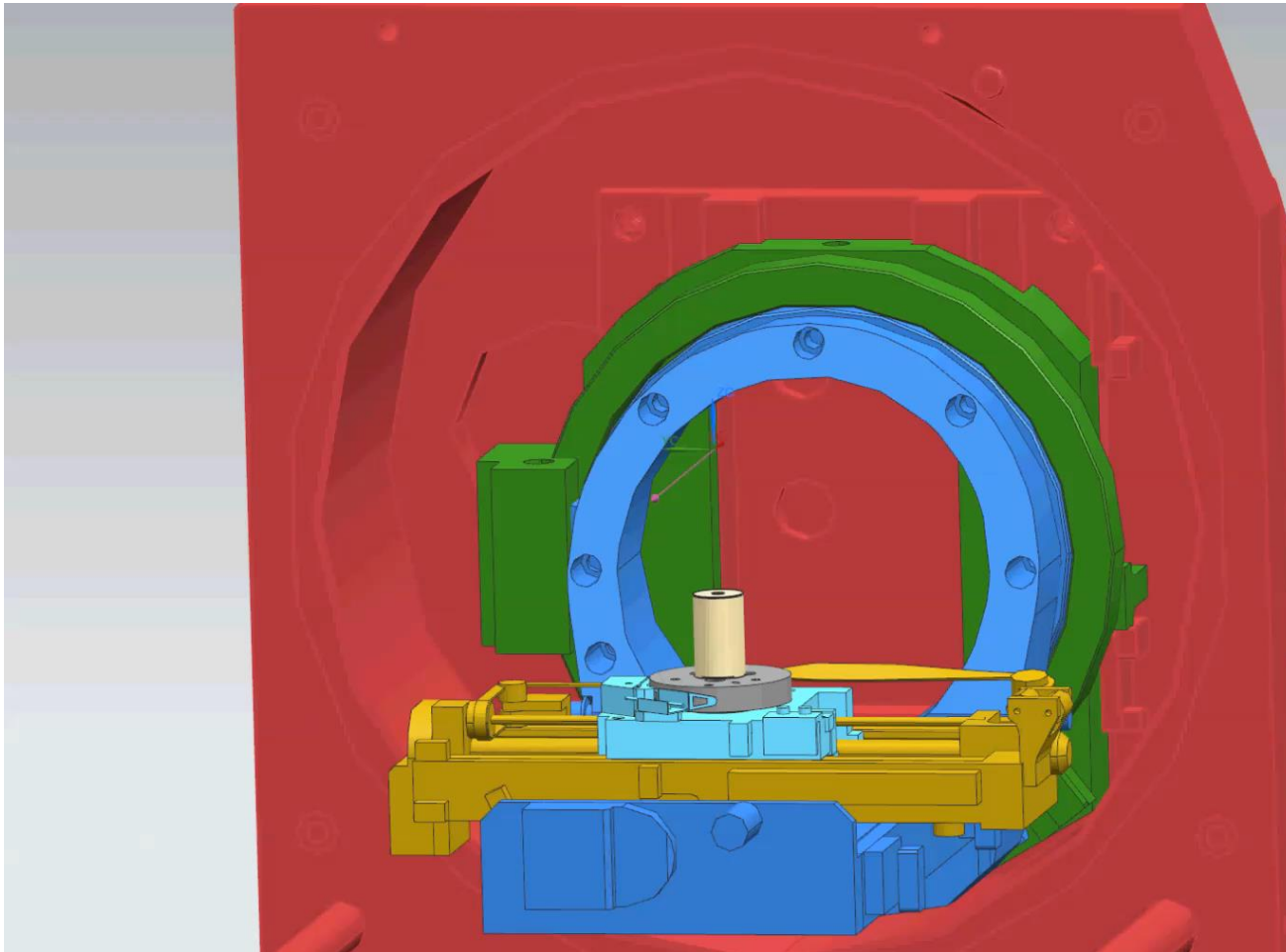
### Non Eucetric stage

- Z stacked before T
- Compensation in Y needed



# General requirements for sample manipulator

## Eucentricity

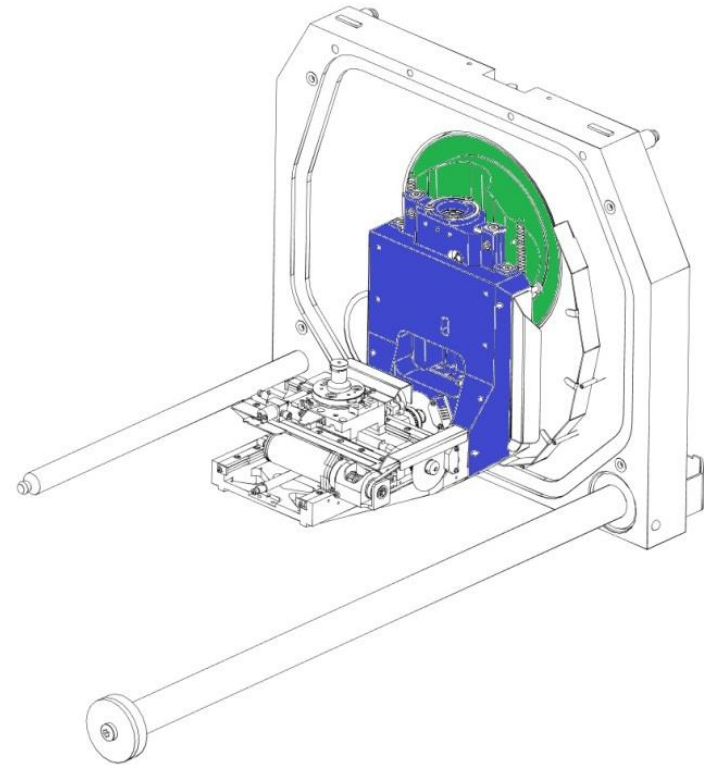
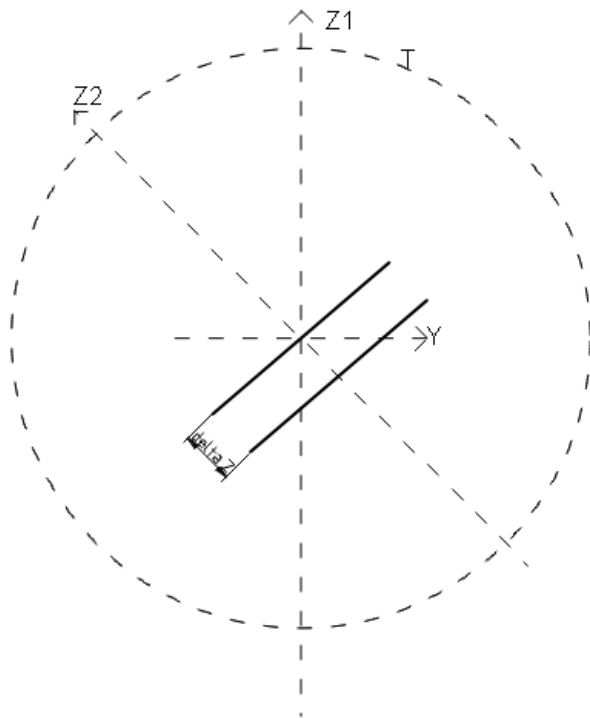


# General requirements for sample manipulator

## Eucentricity

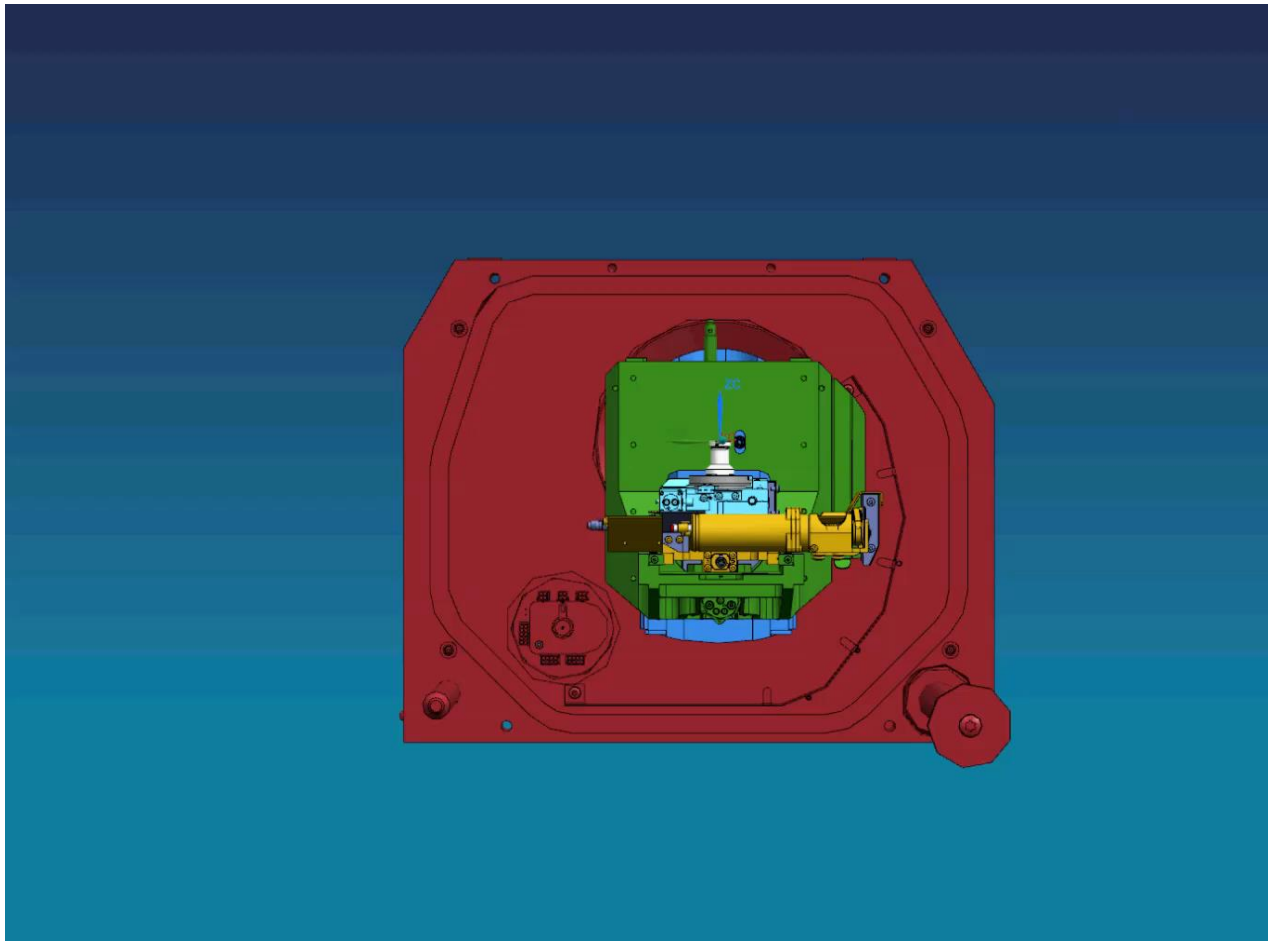
### Eucetric stage

- T stacked before Z
- Preferable for SEM/FIB



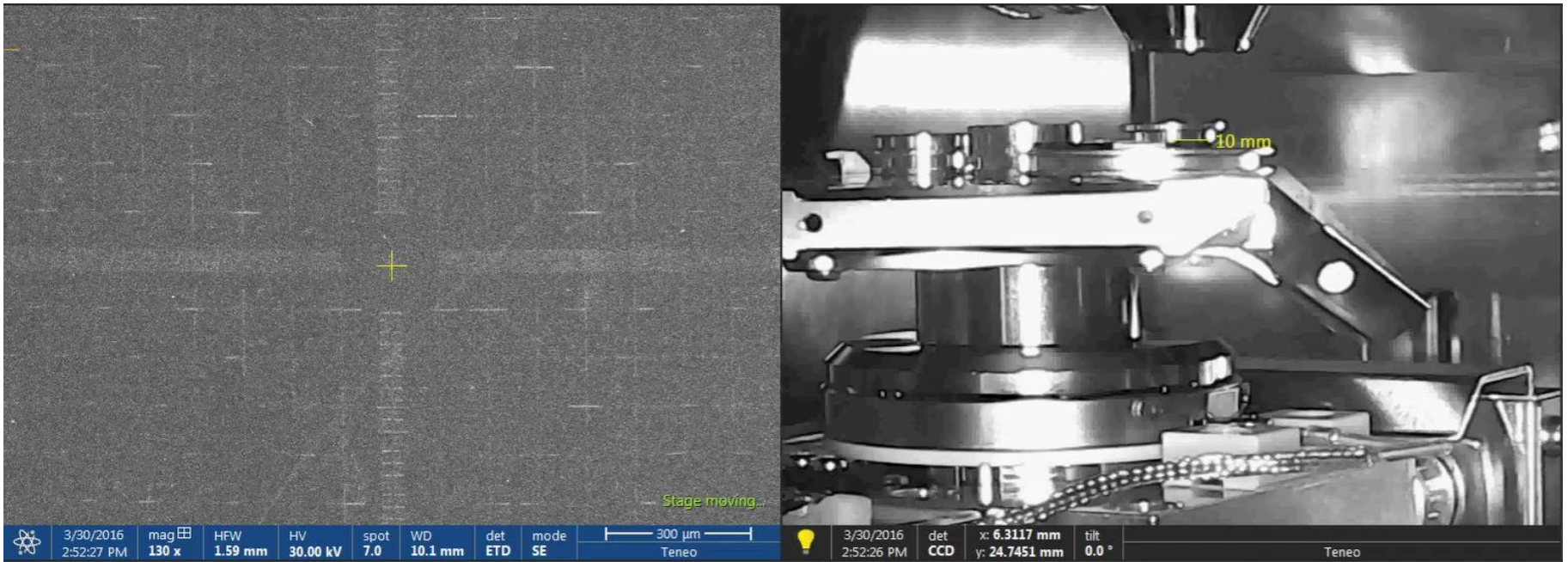
# General requirements for sample manipulator

## Eucentricity



# General requirements for sample manipulator

## Eucentricity





# General requirements for sample manipulator

## System compliance

### **Vacuum compatibility to reduce contamination**

- Avoid soft plastics, Zinc (brass), magnesium, cadmium, anodizing, paints...
- Use PEEK, steel, aluminium alloys, bronze, chemical nickel plating

### **Magnetic compatibility to not to distort beams**

- Avoid magnetic materials – steel, iron, electrolytic nickel plating
- Use Aluminium alloys, stainless steel
- AC fields are problematic (motors)
- DC shifts beams predictably

### **Chemical resistance to gas chemistry**

- Non reactive surfaces – gold plating if needed

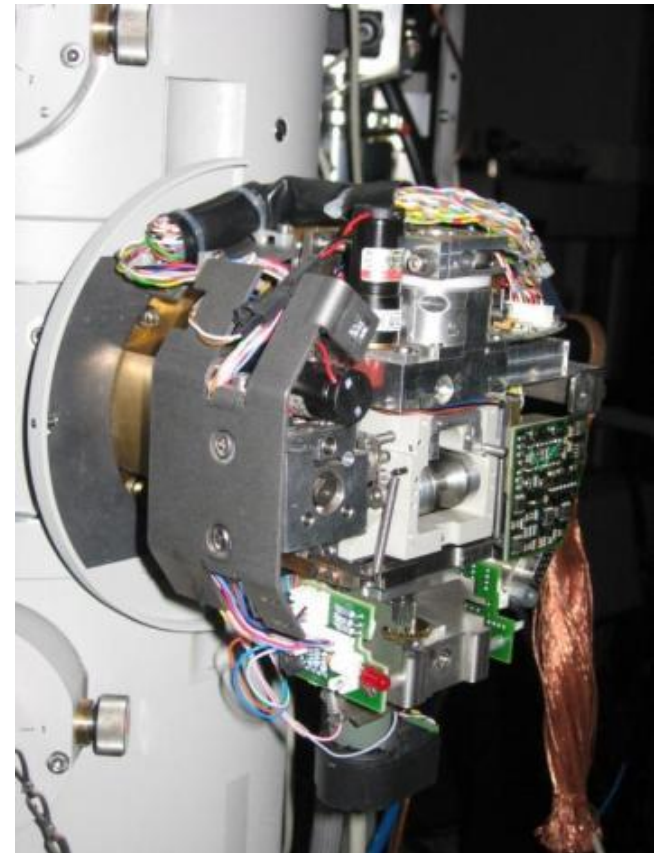
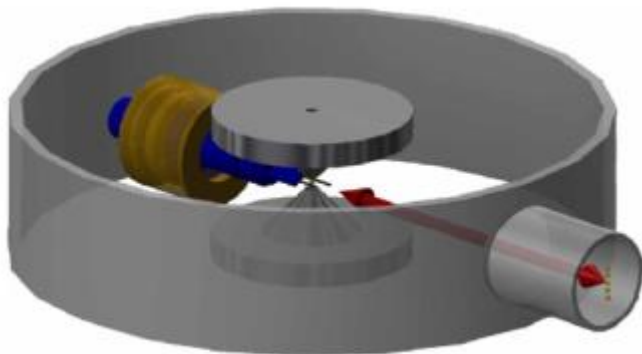
### **Vacuum tightness**

- Consider electrical feedthrough, dynamic seals
- $1e-8$  mbar\*l/s



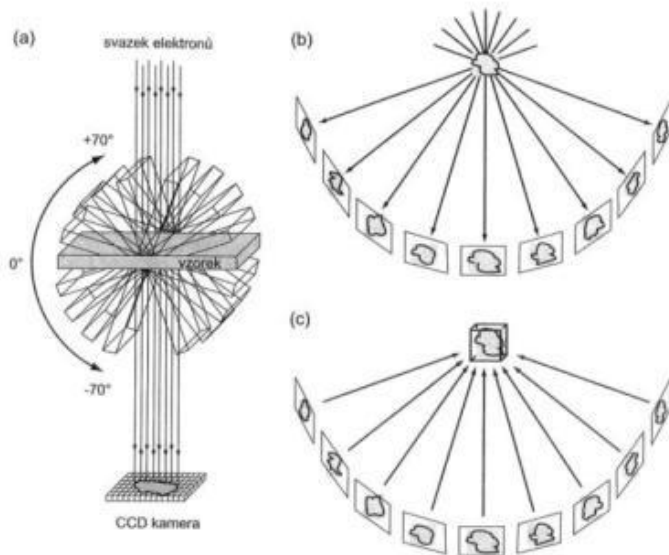
# TEM stages

- **Mounted on the column**
  - At atmosphere
- Inserts sample on a holder into objective lens
- Additional functionality achieved by sample holders

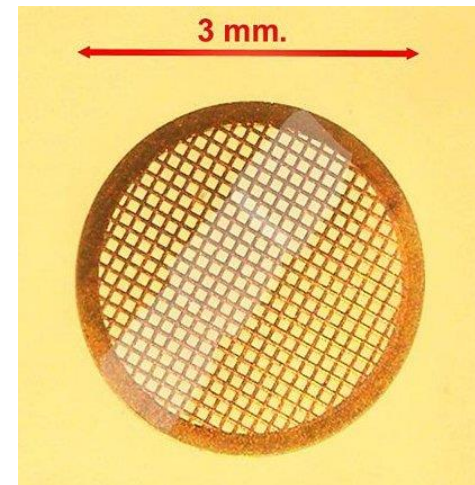


# TEM stages

- Movement ranges to accommodate standard  $\varnothing$  3 mm sample (TEM grid) and use case
- Sample size is a compromise between magnification needed and practicality
- Tilt axis for 3D reconstruction

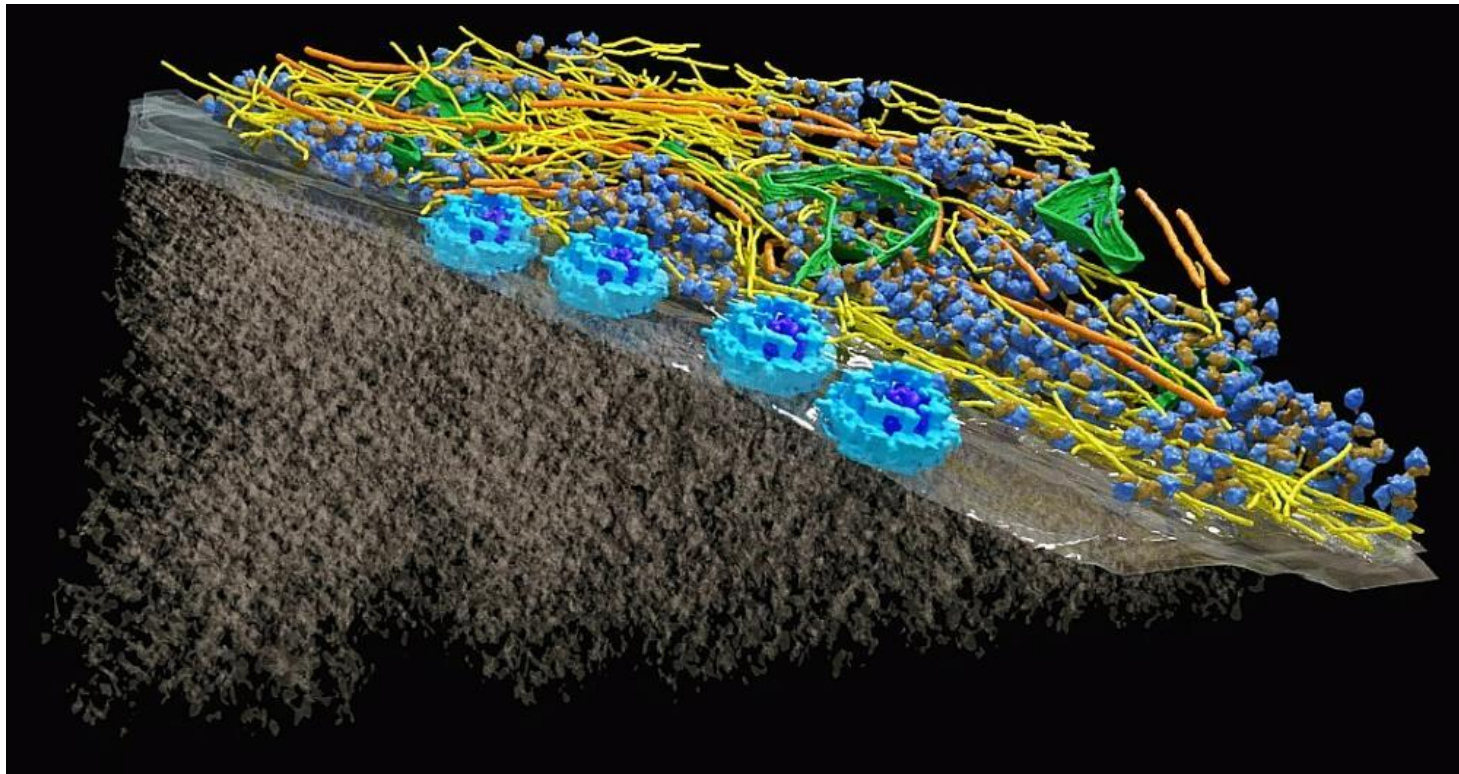


Obr. 9.41. Schéma elektronové tomografie a 3D rekonstrukce: (a) Registrace série snímků při postupném naklápění vzorku v rozmezí úhlů  $\pm 70^\circ$ , (b) Průměty objektu na jednotlivých snímcích, (c) Zpětná počítačová rekonstrukce původního trojrozměrného objektu. Upraveno podle [SB05].



# TEM stages

- Tilt axis for 3D reconstruction



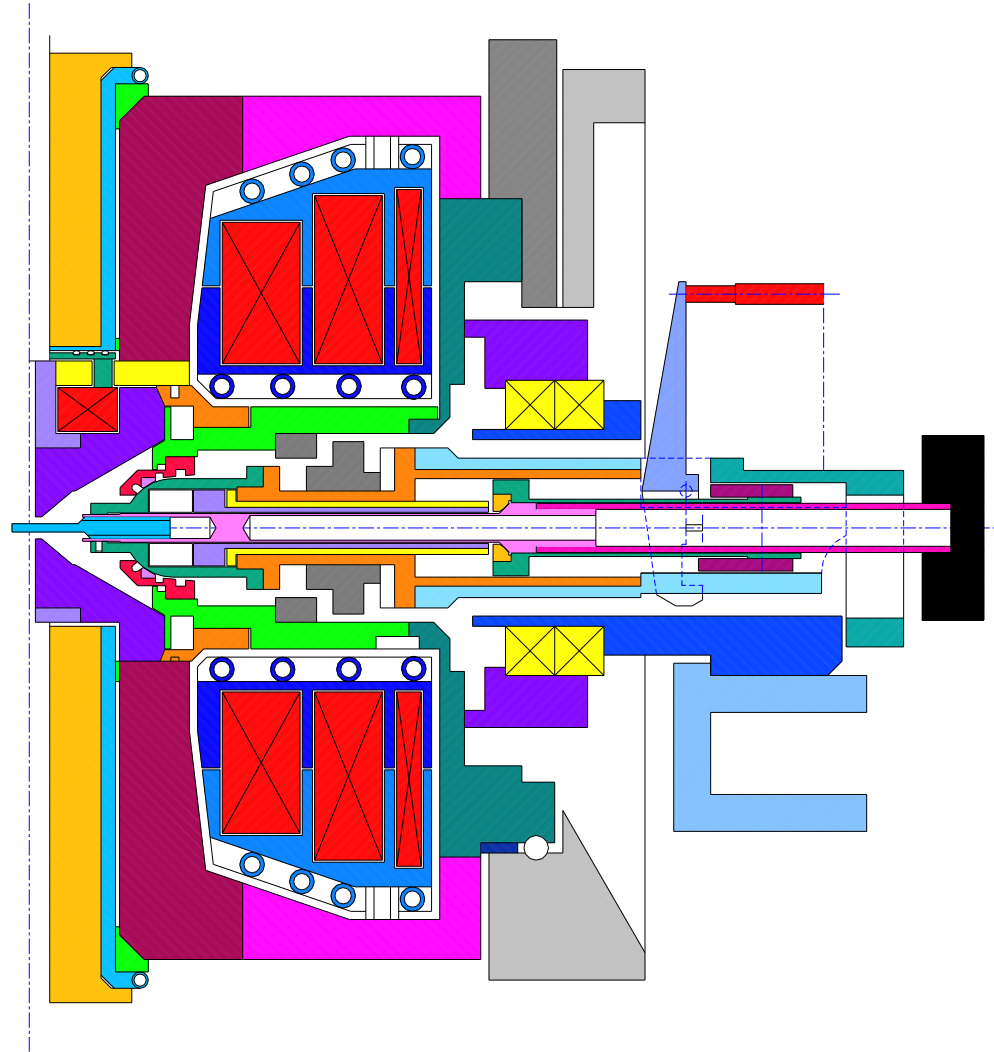
# TEM stages design

## Example parameters

- XY range  $\pm 1.5\text{mm}$
- Z range  $\pm 0.375\text{ mm}$
- Tilt  $\pm 90^\circ$
- Specimen drift  $< 0.5\text{nm/min}$
- Smallest steps in nanometres

## Design principles

- Flexure design
- Paralelograms, lever mechanisms
- Pretension in gears
- Tuned mass damper
- Friction brakes
- DC or piezo driven





# TEM stages - sample holders - extra functionality

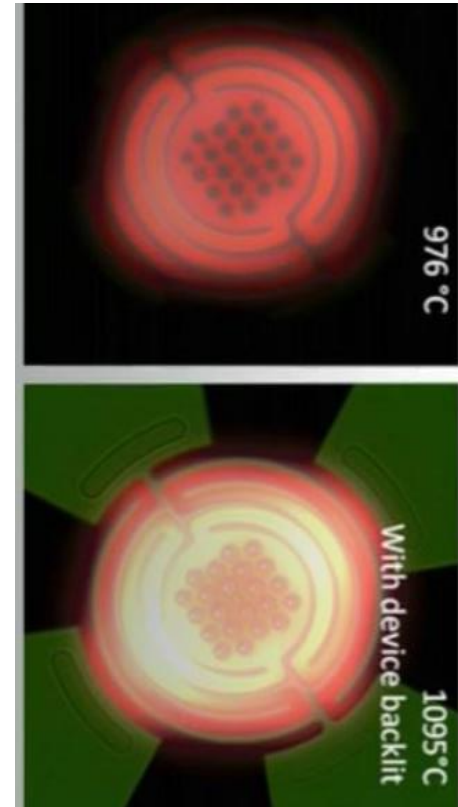
Multisample



Double tilt

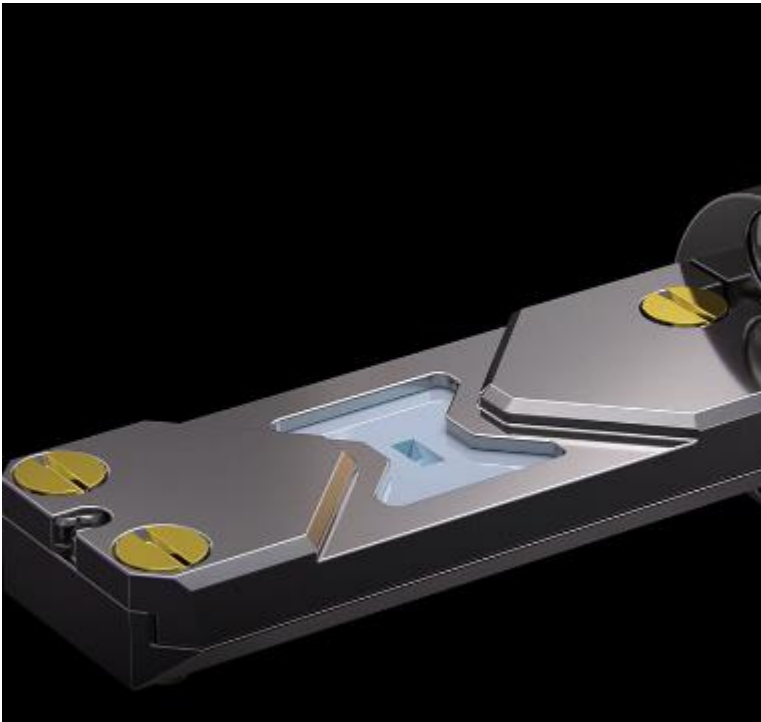


Hot

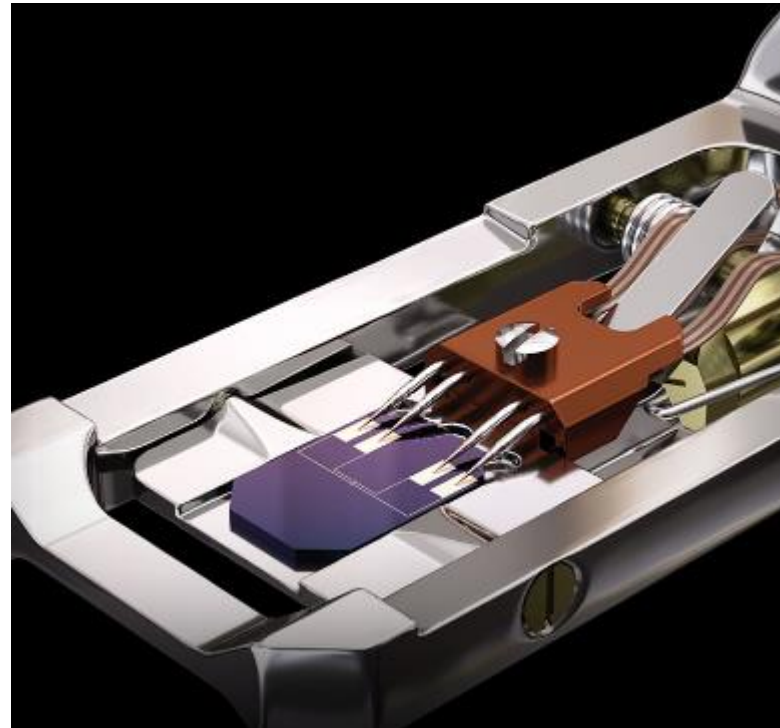


# TEM stages - sample holders - extra functionality

Ambient



Electrical



# SEM stages

## Operate inside a vacuum chamber

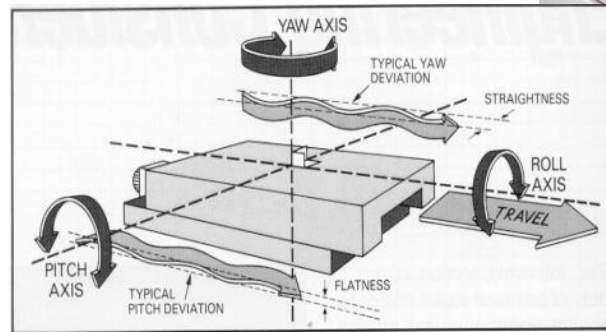
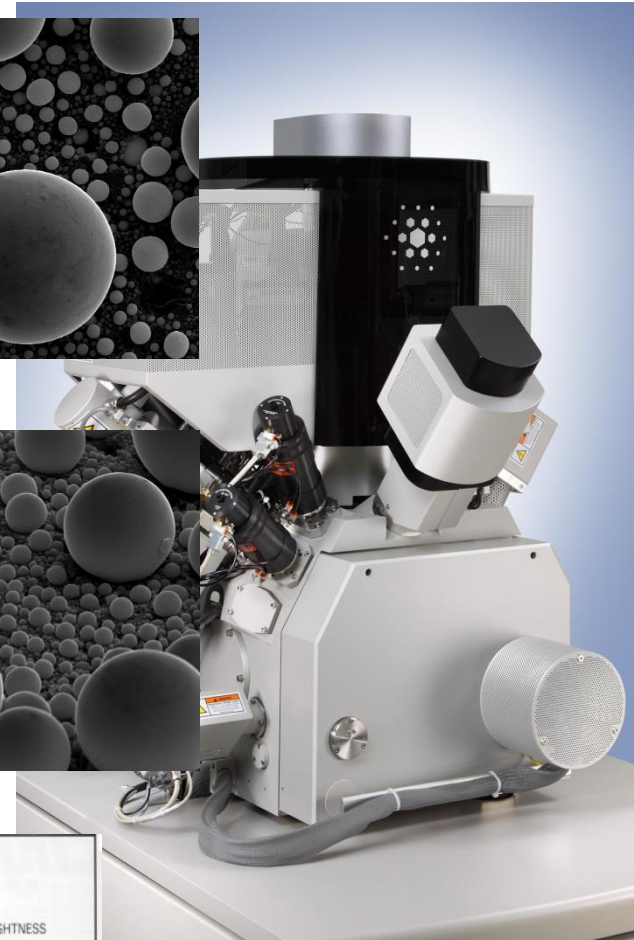
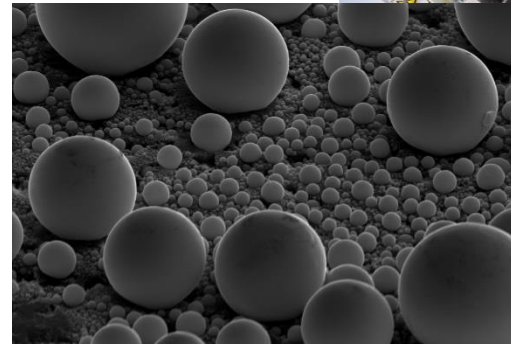
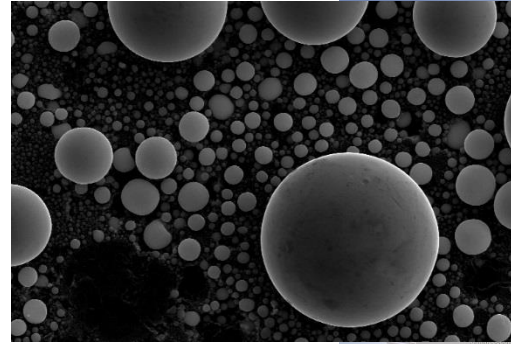
- On chamber door
- On bottom of chamber

## High movement ranges

- 100x100mm XY
- Wafer inspection, mineralogy
- Accessories operation – load lock, STEM detectors...
- Influence of yaw, pitch, roll errors in linear guides

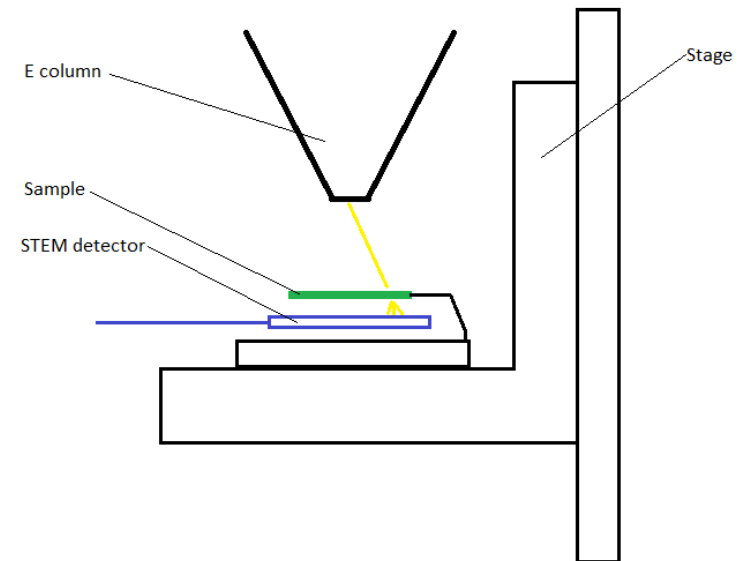
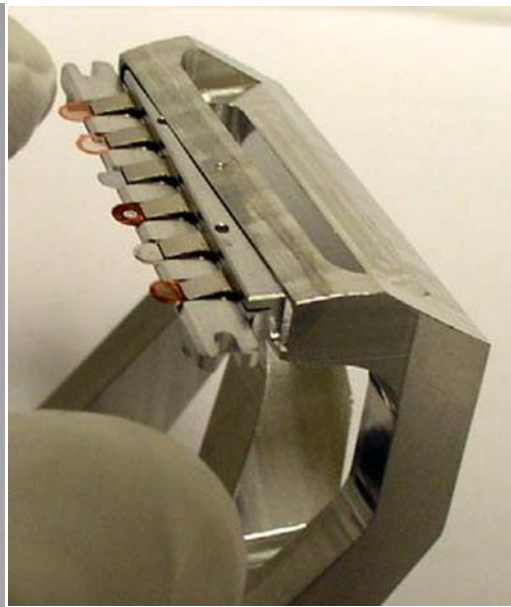
## Tilt axis

- SEM and FIB beam planes
- Topography information



# SEM stages sample holders

- For single or multiple samples
- Stiff
- Conductive - grounding
- Can bring extra functionality - STEM

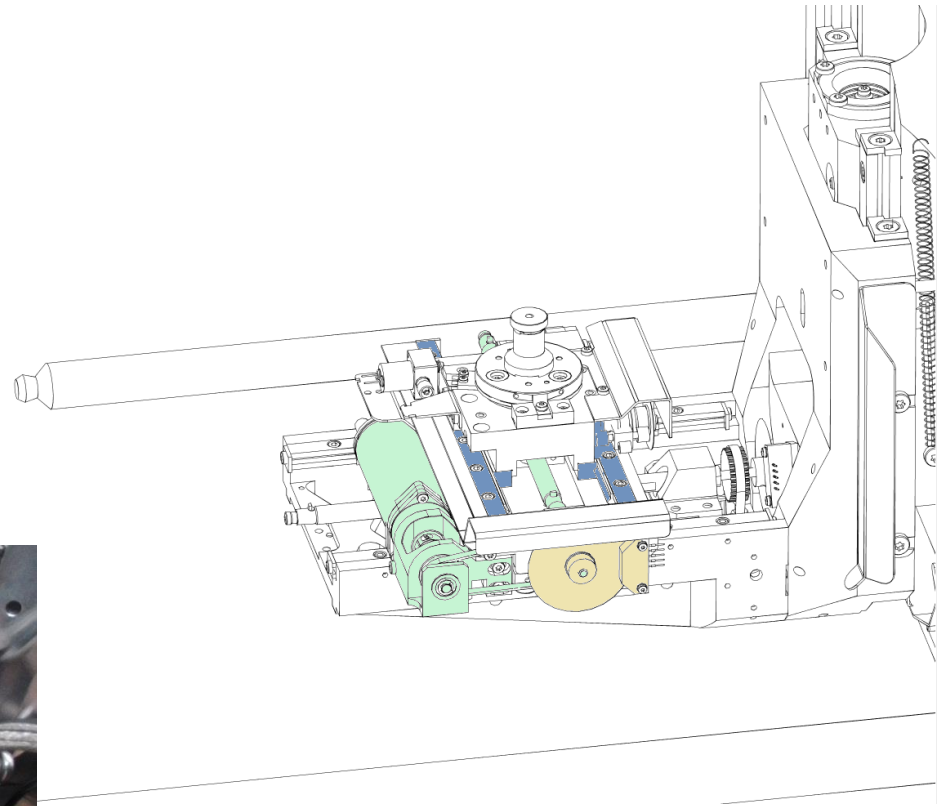
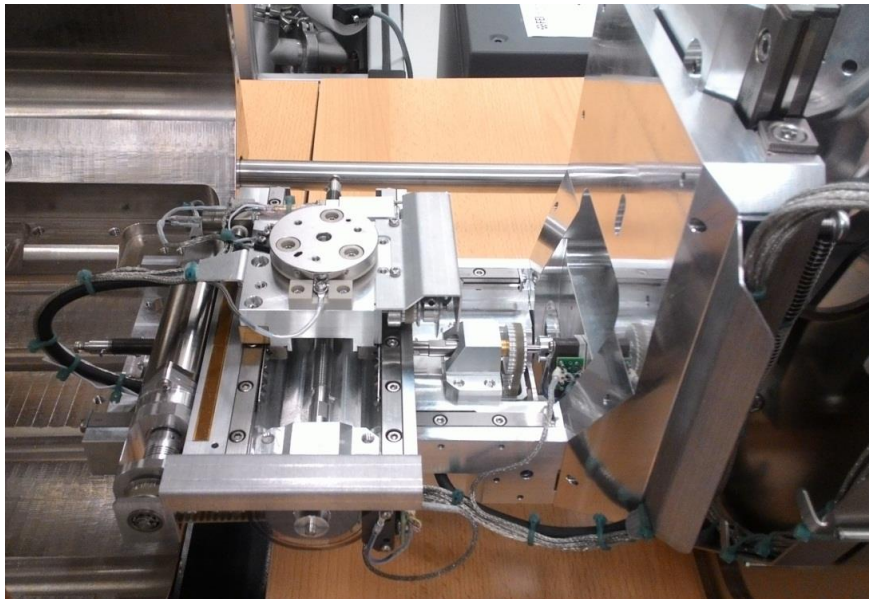




# SEM stages spindle drive

## Spindle & nut, rotary motor

- Accuracy  $<5\mu\text{m}$
- Repeatability  $<2\mu\text{m}$
- Drift  $<20\text{nm}/\text{min}$
  
- Simple
- **Not so expensive**



# SEM stages spindle driven

But there are design challenges

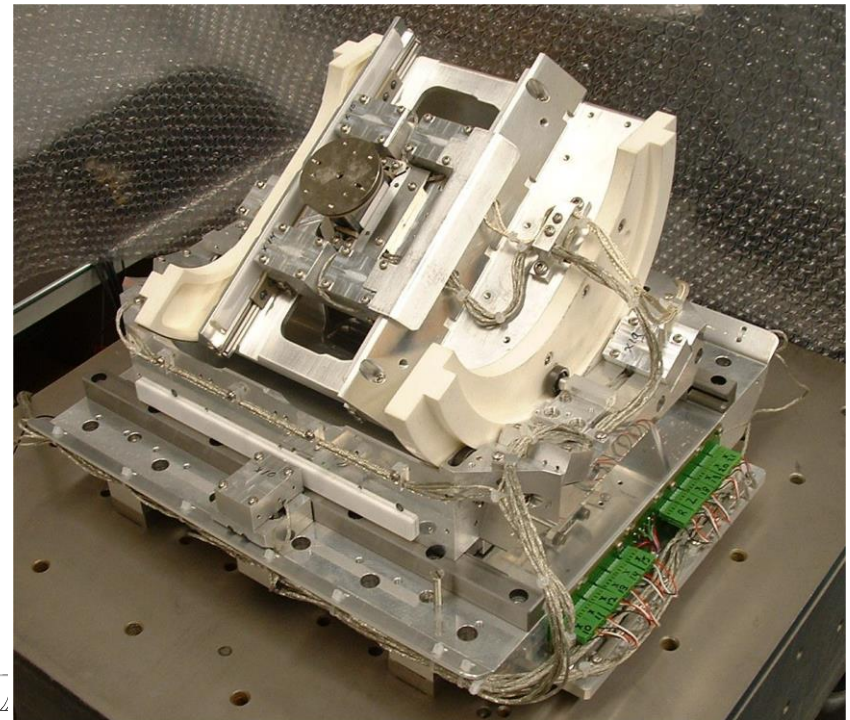
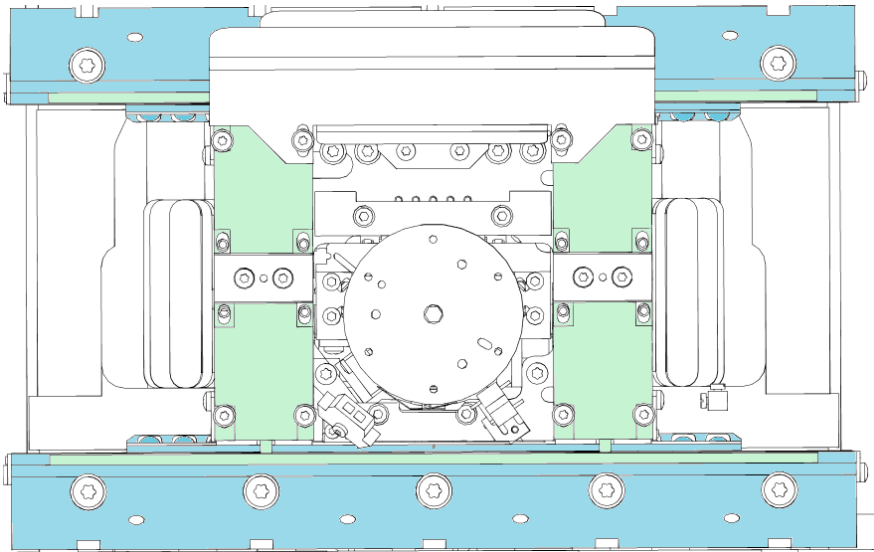
- Relatively lower stiffness
- Lower axis acceleration and speed
- Motor shielding
- Remove play in gears



# SEM stages piezo driven

## Direct piezo drive

- Accuracy  $<0.5\mu\text{m}$
- Repeatability at smallest step level (with linear encoders)
- Drift  $<8\text{nm}/\text{min}$
- **For highend systems**
- Great stiffness and dynamics
- No play
- Easy to be non magnetic
- Pricy



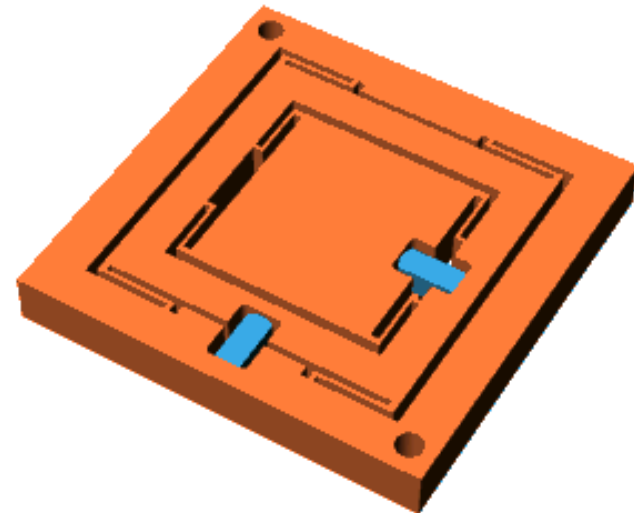
# SEM stages substages

## Piezo driven flexures

- Flexible joints only – no friction at all
- Piezo stacks
- Subnanometer steps
- Substage or for AFM



<http://www.physikinstrumente.com/products/xyz-nanopositioning-stages.html>



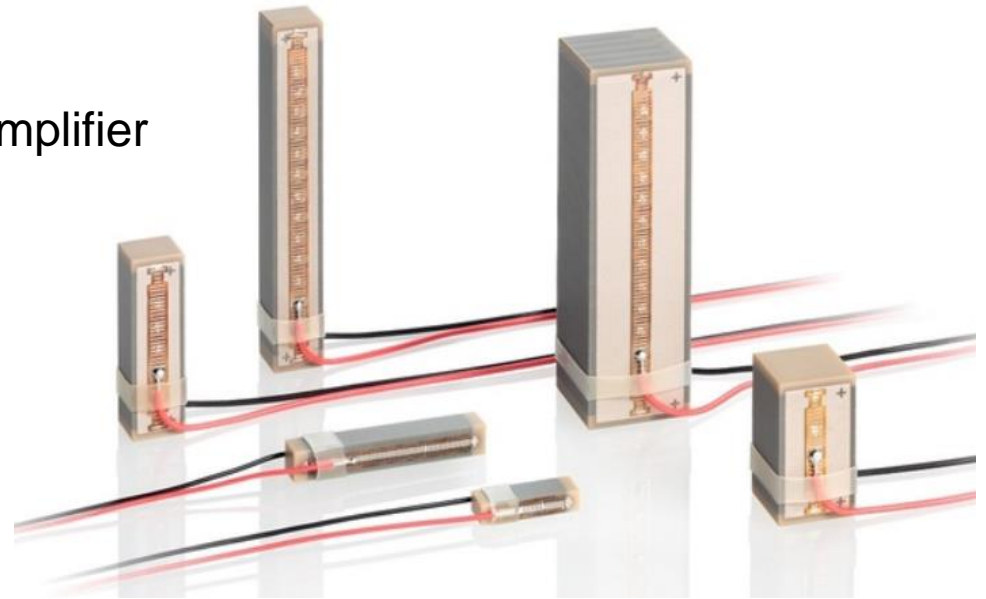
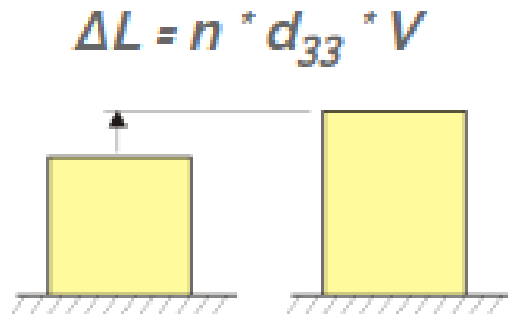
<http://www.piezostage.net/>

# Piezo motor principles

**Indirect piezoelectric effect** – change of shape of a crystal by voltage applied to it

## Piezo stack

- Stacked piezo crystals – direct actuation
- Most accurate
  - DC voltage
  - Depends on quality of drive amplifier
- Micrometer ranges

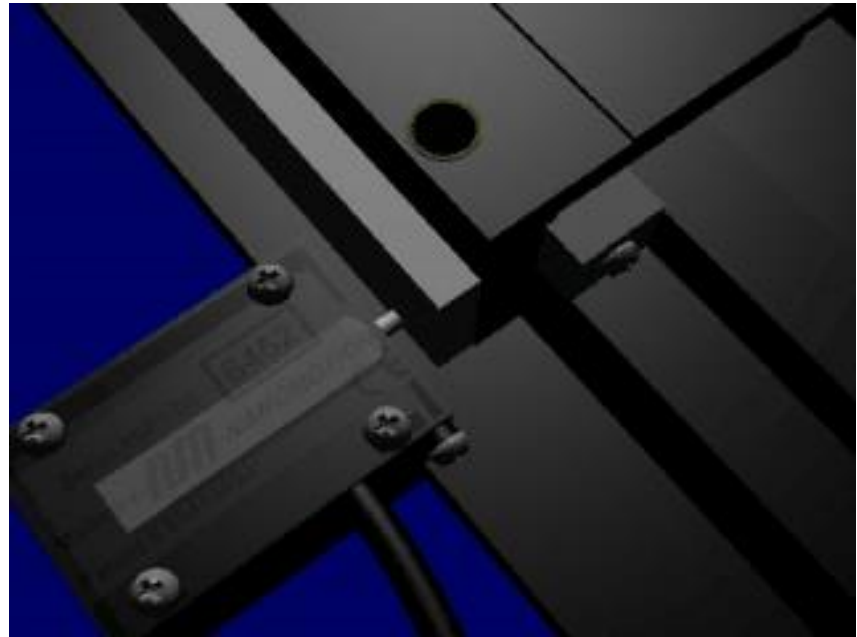
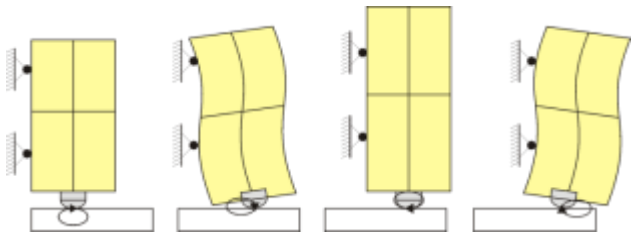


<https://www.physikinstrumente.com/en/products/piezoceramic-actuators/linear-actuators/p-882-p-888-picma-stack-multilayer-piezo-actuators-100810/>

# Piezo motor principles

## Ultrasonic

- 40kHz AC excitation, 300V<sub>RMS</sub>
- High speed - meters per second
- Discrete steps with voltage period  $\pm 100\text{nm}$



<http://www.nanomotion.com/support-downloads/product-videos/>



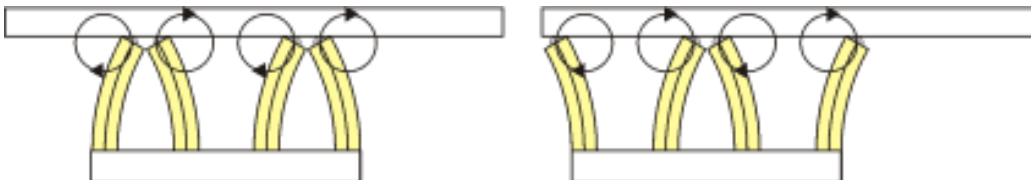
# Piezo motor principles

## Walking leg

- Equivalent of a standard stepper – including microstepping  $\pm 1\text{nm}$
- Lower speeds
- Low wear



<https://www.youtube.com/watch?v=Z45PWSGpc8A>

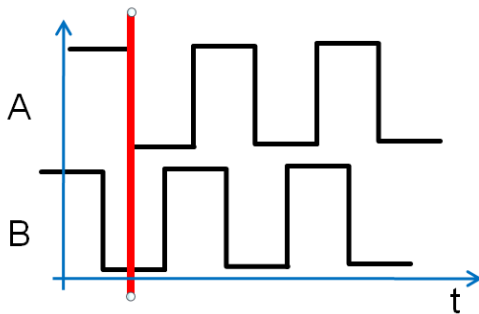
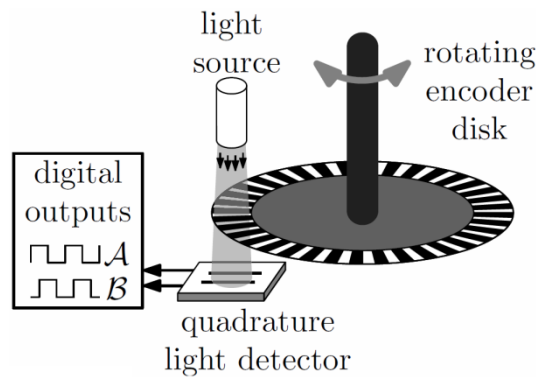


# Position feedback - encoders

## Optical encoders

Incremental or absolute

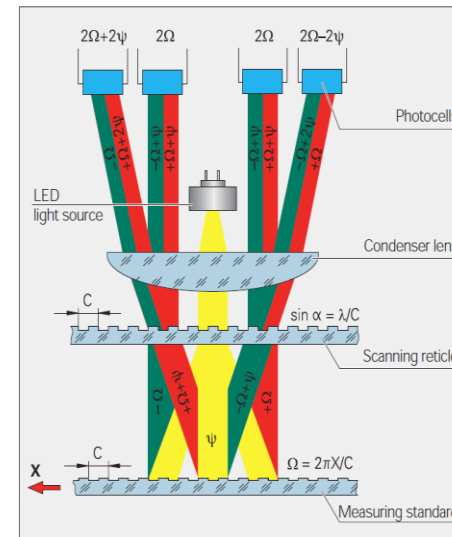
### Rotary



### Linear - interferometric

Interferential scanning principle (optics schematics)

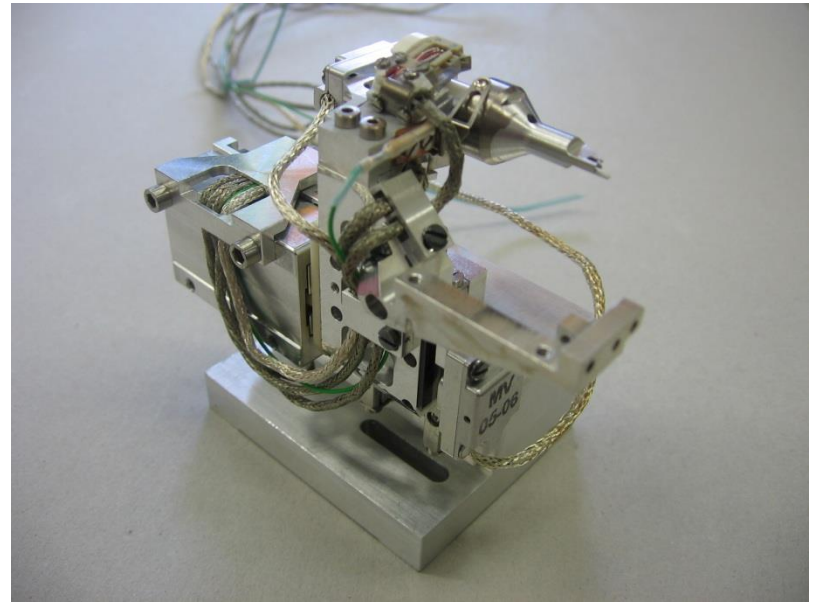
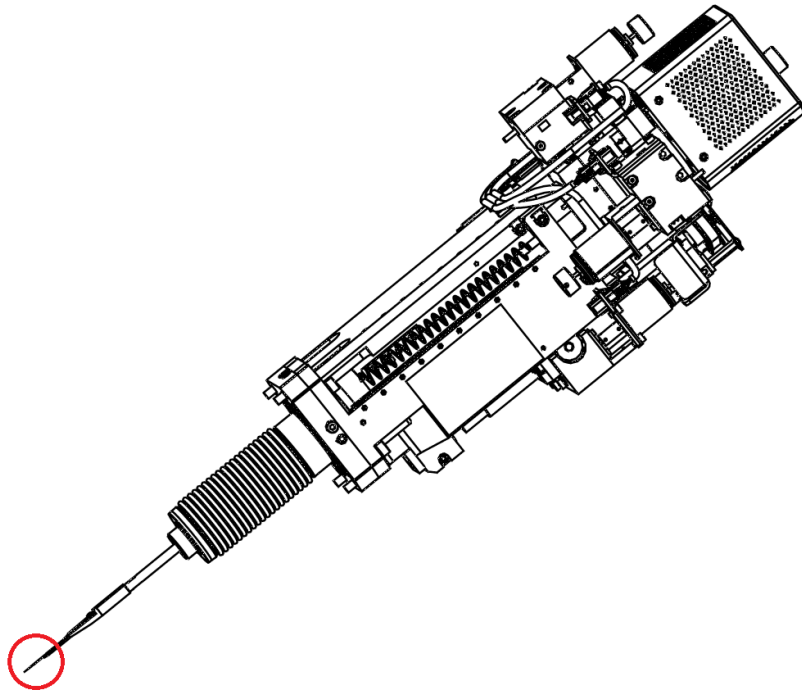
- C Grating period
- $\psi$  Phase shift of the light wave when passing through the scanning reticle
- $\Omega$  Phase shift of the light wave due to motion X of the scale



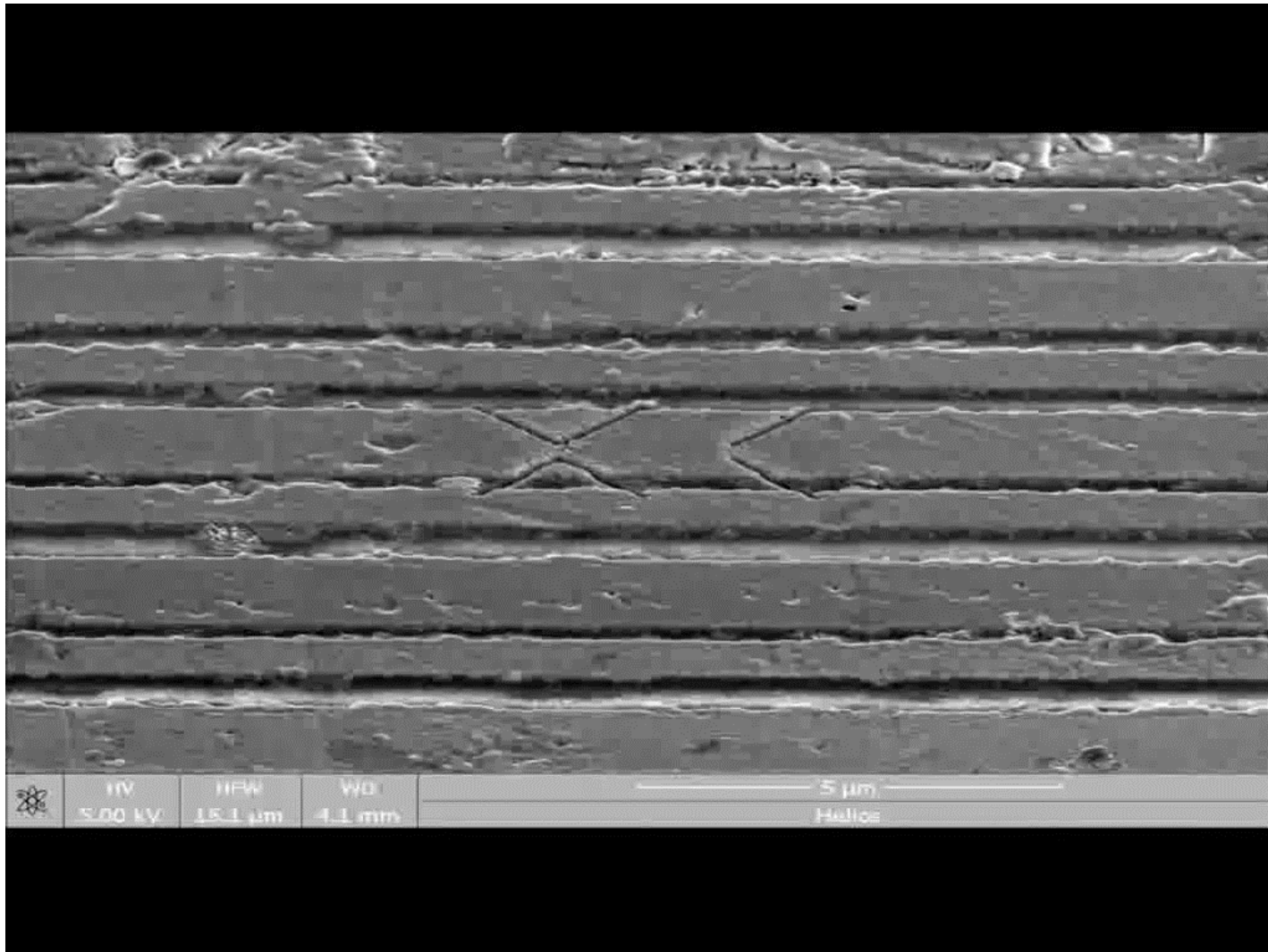


# TEM sample preparation

Extraction of a lamella from a bulk sample using SEM/FIB

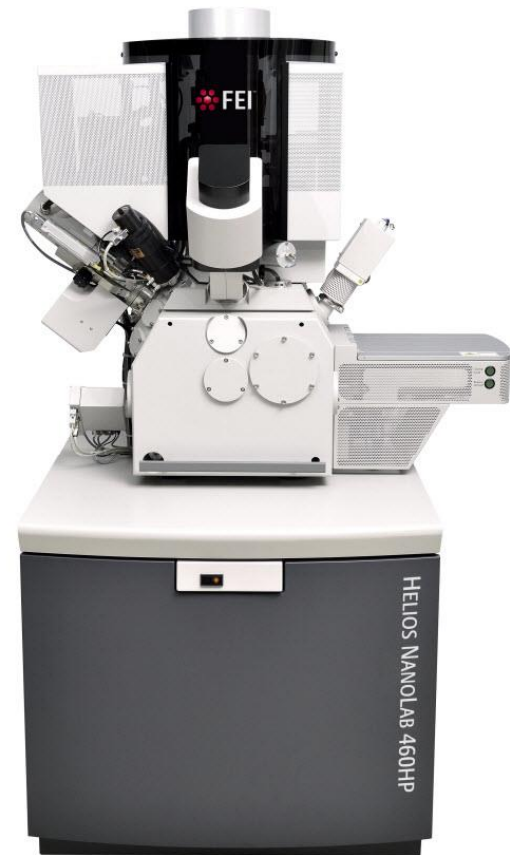
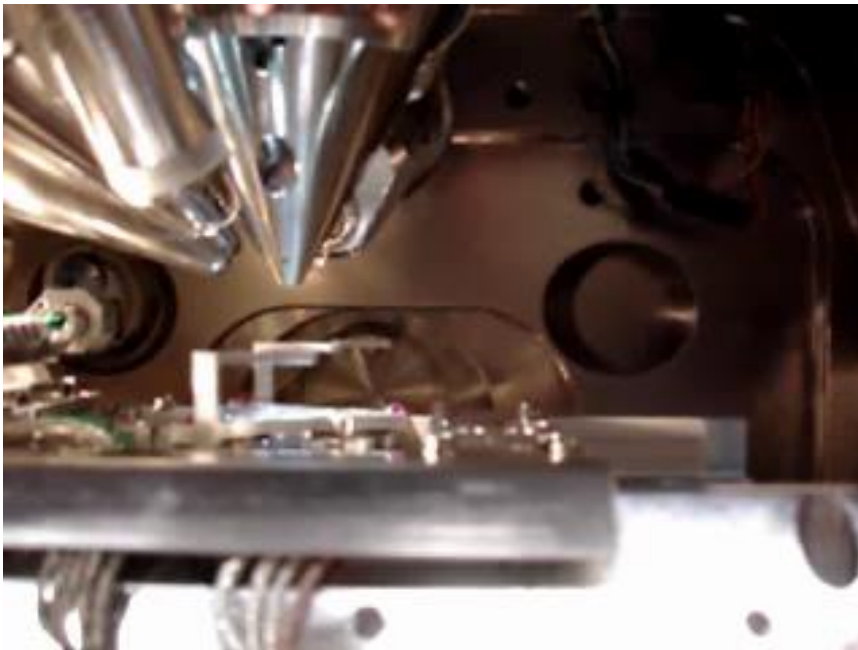


# TEM sample preparation

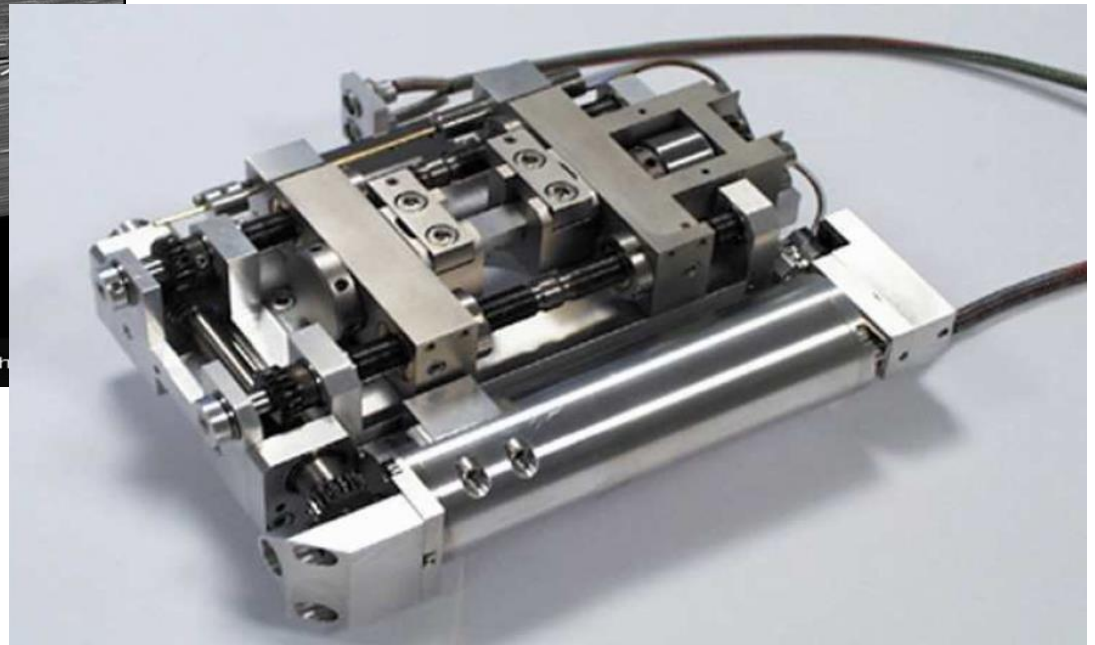
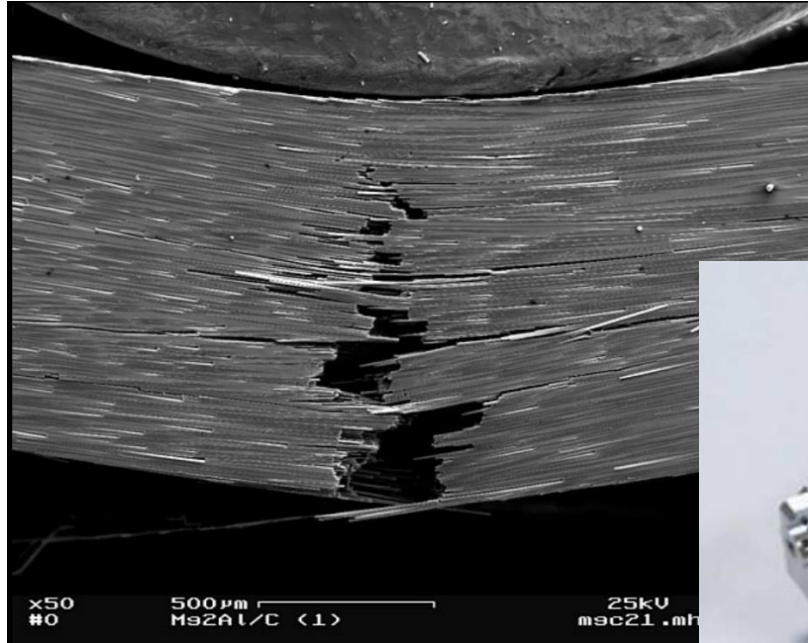


# Additional equipment - loadlock

- Shortening pumping cycle
- Reducing vacuum contamination

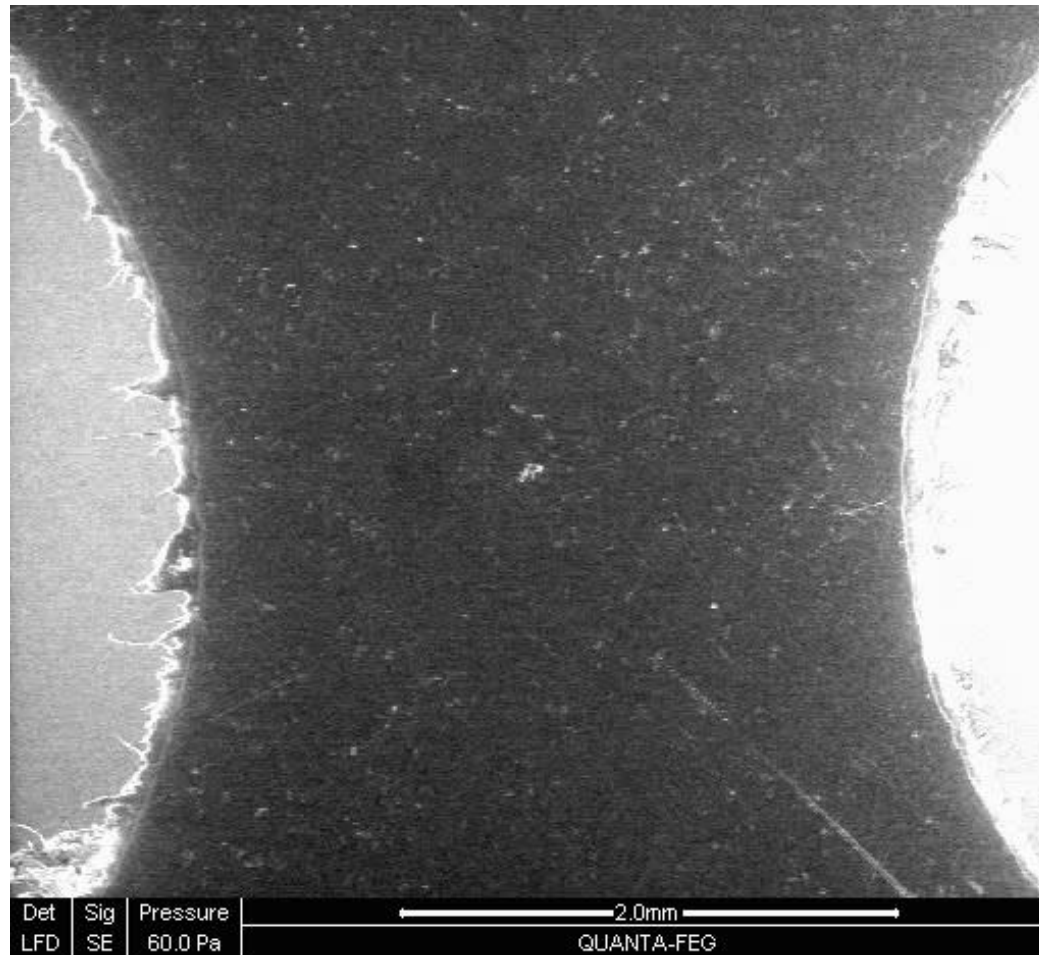


# Additional equipment - Mechanical material testing

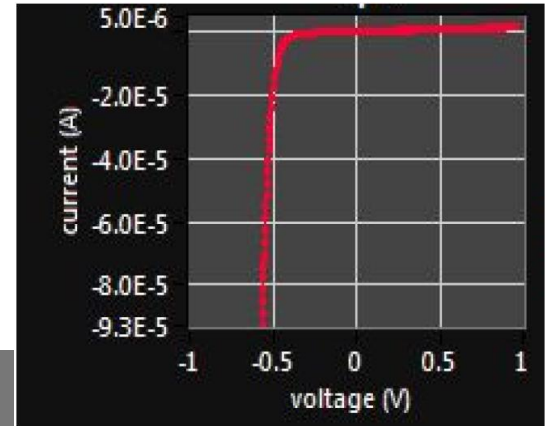
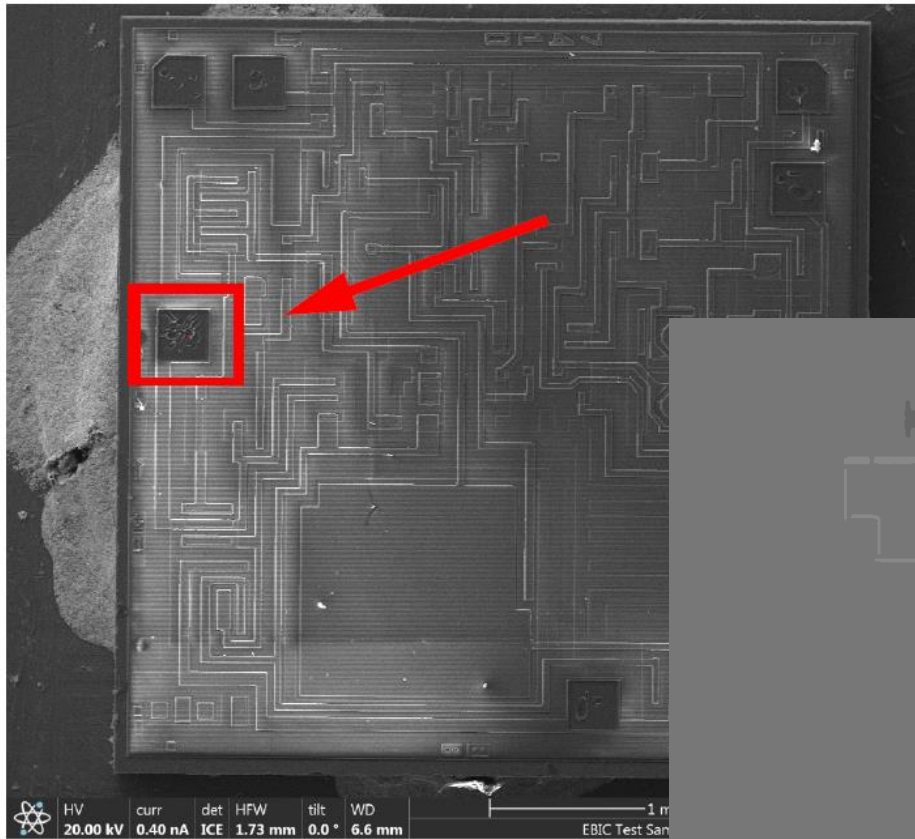




# Additional equipment - Mechanical material testing

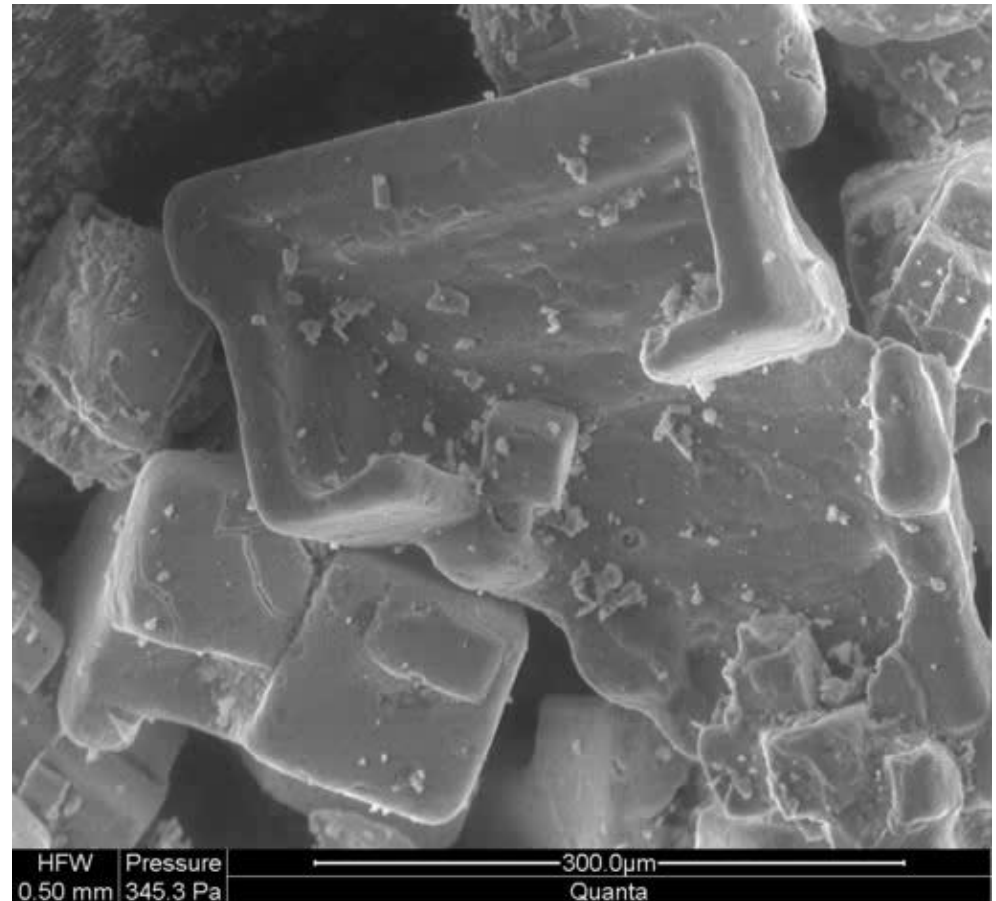
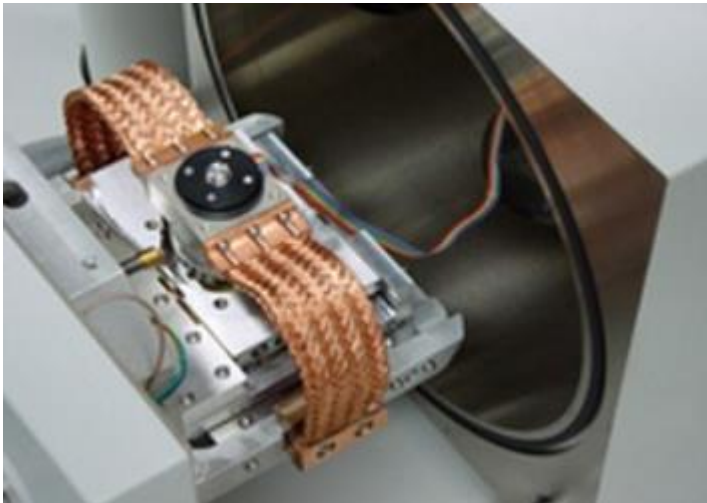


# Additional equipment - Electrical failure analysis



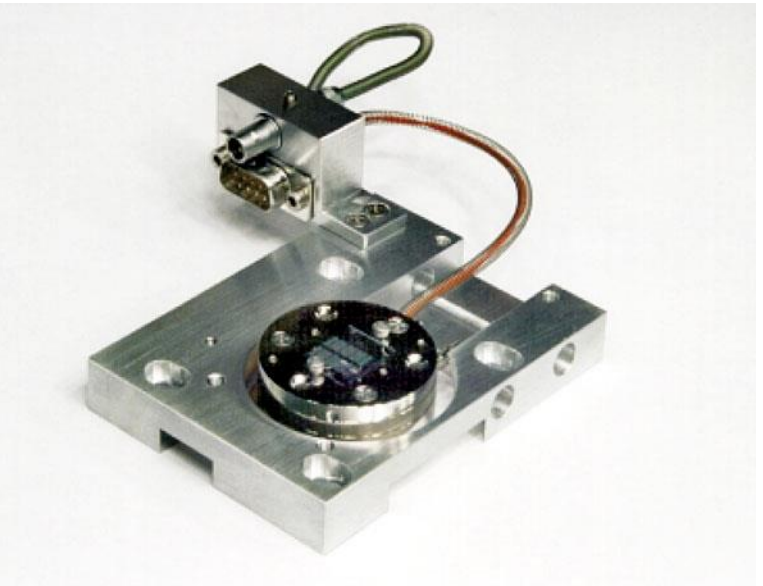
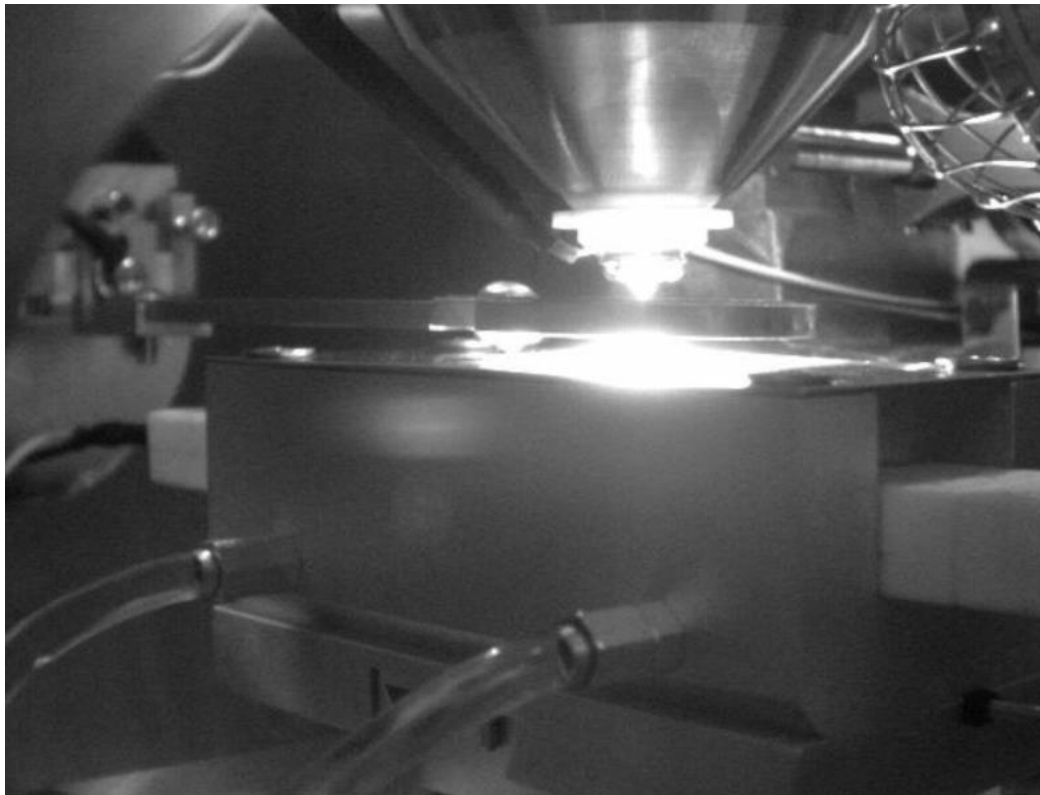
# Additional equipment - cold stage

- In-situ observation of thermal processes
- Peltier stage > -100°C
- Cryo N2 > -190°C – biology



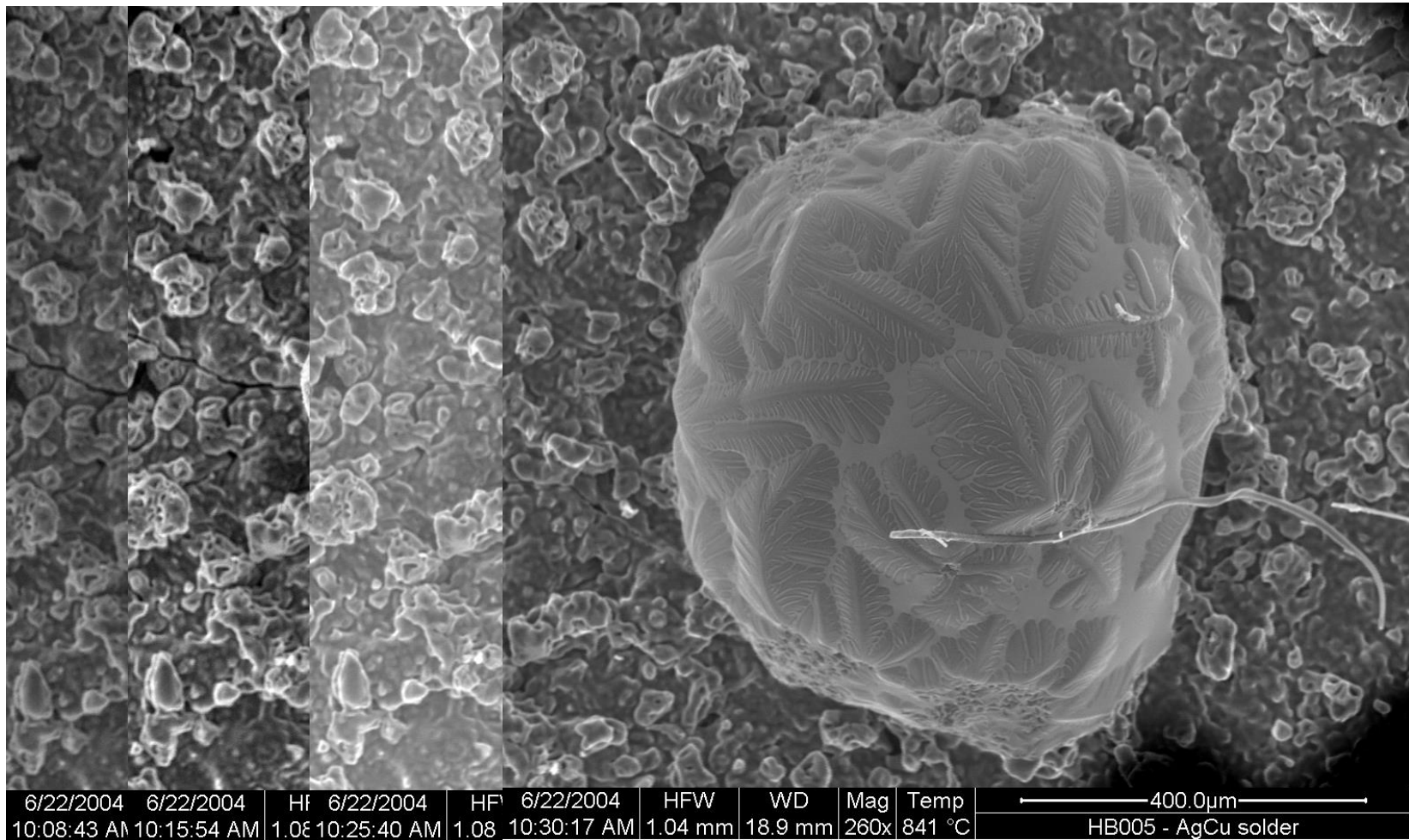
# Additional equipment - hot stage

- Low temperature  $< 400^{\circ}\text{C}$
- Mid temperature  $< 1000^{\circ}\text{C}$  – shielding needed from thermal electrons
- High temperature  $< 1400^{\circ}\text{C}$  – special material requirements, lifetime in hours





# Additional equipment - hot stage



Melting and recrystallization of AgCu solder